

ABSTRACT OF THE DISCLOSURE

The invention provides semiconductor devices that are excellent in manufacturing efficiency, and provides highly reliable semiconductor devices, circuit substrates and electronic equipment. A method of manufacturing a semiconductor device in accordance with the present invention includes: providing liquid resin on a first semiconductor chip, which is mounted on a substrate having wiring patterns; mounting a second semiconductor chip over the first semiconductor chip through the liquid resin; and hardening the liquid resin to form a spacer between the first semiconductor chip and the second semiconductor chip, and to fix the first and second semiconductor chips together.